BTA216B series D, E and F

GENERAL DESCRIPTION

Passivated guaranteed commutation triacs in a plastic envelope suitable for surface mounting, intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

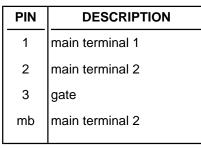
PINNING - SOT404

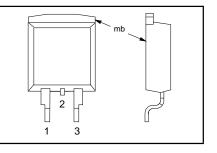
QUICK REFERENCE DATA

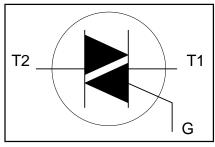
SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V _{drm} I _{t(rms)} I _{tsm}	BTA216B- BTA216B- BTA216B- BTA216B- Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	600D 600E 600F 600 16 140	- 800E 800F 800 16 140	V A A
1				

PIN CONFIGURATION

SYMBOL







LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.	
V _{drm}	Repetitive peak off-state voltages		-	-600 600 ¹	-800 800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; T _{mb} ≤ 99 °C	-	16	3	A
I _{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25 \degree C$ prior to surge t = 20 ms	-	14	0	A
l²t dI _T /dt	I ² t for fusing Repetitive rate of rise of on-state current after triggering		-	15 98 10	3	Α A²s A/μs
$\begin{array}{l} I_{GM} \\ V_{GM} \\ P_{GM} \\ P_{G(AV)} \end{array}$	Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms period	- - -	2 5 5 0.		A V W W
T _{stg} T _j	Storage temperature Operating junction temperature	penou	-40 -	15 12	-	С° С

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb} R _{th j-a}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle minimum footprint, FR4 board	-	- - 55	1.2 1.7 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
		BTA216-		D	D	E	F	
I _{GT}	Gate trigger current ²	V _D = 12 V; I _T = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	1.3 2.6 3.4	5 5 5	10 10 10	25 25 25	mA mA mA
IL	Latching current	V _D = 12 V; I _{GT} = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	10.2 11.3 19.3	15 25 25	25 30 30	30 40 40	mA mA mA
I _H	Holding current	V _D = 12 V; I _{GT} = 0.1 A	-	8	15	25	30	mA
				•	D, E, F	•		
V _T V _{GT}	On-state voltage Gate trigger voltage	$ \begin{aligned} I_T &= 20 \text{ A} \\ V_D &= 12 \text{ V}; \ I_T &= 0.1 \text{ A} \\ V_D &= 400 \text{ V}; \ I_T &= 0.1 \text{ A}; \\ T_i &= 125 \text{ °C} \end{aligned} $	- - 0.25	1.2 0.7 0.4		1.5 1.5 -		V V V
I _D	Off-state leakage current	$V_{D} = V_{DRM(max)};$ $T_{j} = 125 \text{°C}$	-	0.1		0.5		mA

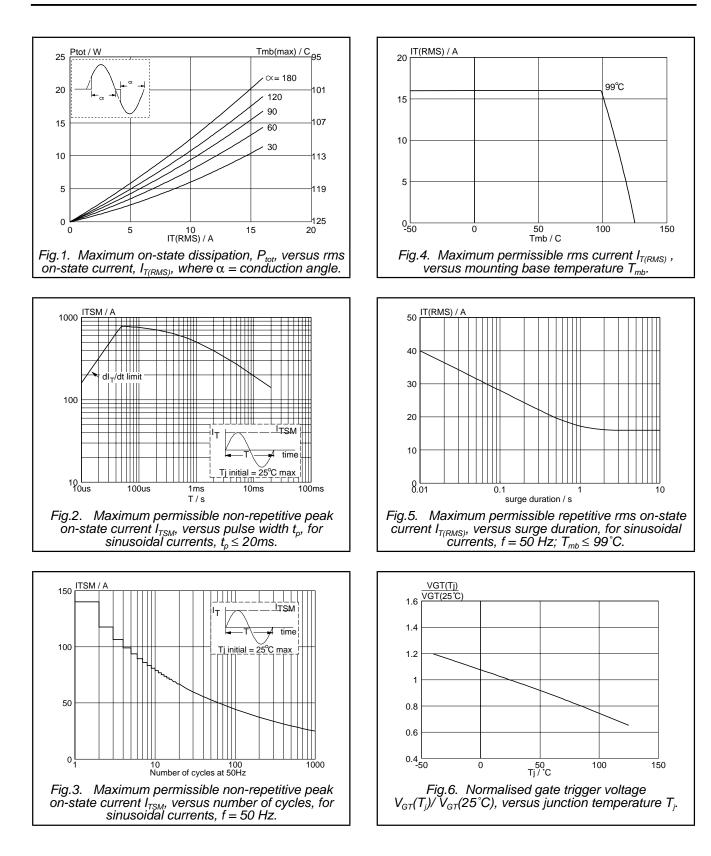
DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

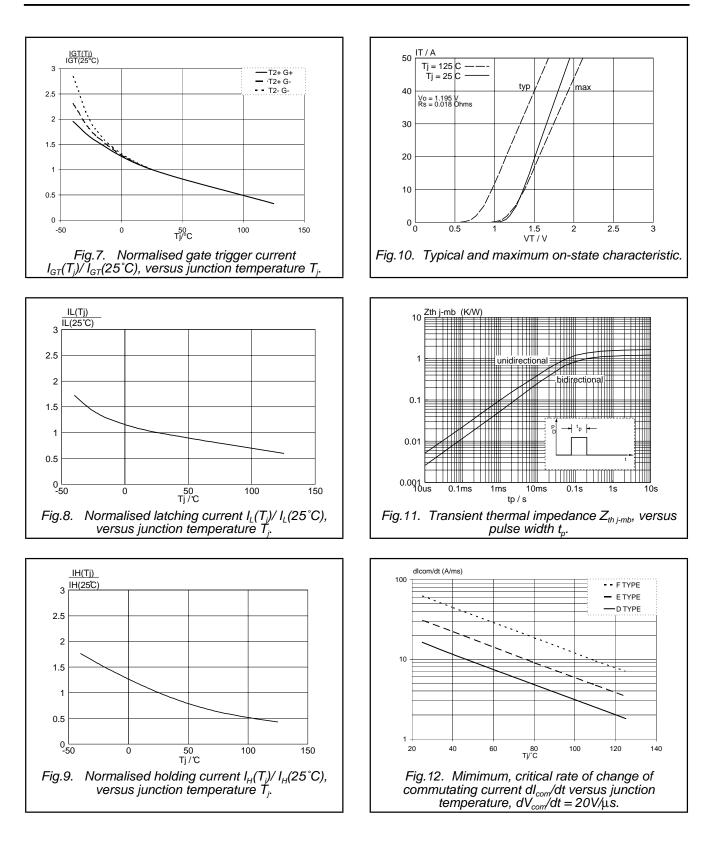
SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
		BTA216-	D	E	F	D		
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)};$ T _j = 110 °C; exponential waveform; gate open circuit	30	60	70	65	-	V/µs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; \text{ T}_{j} = 110 ^{\circ}\text{C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20V/\mu s;$ gate open circuit	2.5	4.7	9.5	7.5	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; \text{ T}_{j} = 110 \text{ °C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 0.1V/\mu \text{s}; \text{ gate}$ open circuit	12	40	50	100	-	A/ms
			D, E, F					
t _{gt}	Gate controlled turn-on time	$ I_{TM} = 20 \text{ A}; V_{\text{D}} = \text{V}_{\text{DRM(max)}}; \\ I_{\text{G}} = 0.1 \text{ A}; \text{dI}_{\text{G}}/\text{dt} = 5 \text{A}/\mu\text{s} $	-	-	-	2	-	μs

2 Device does not trigger in the T2-, G+ quadrant.

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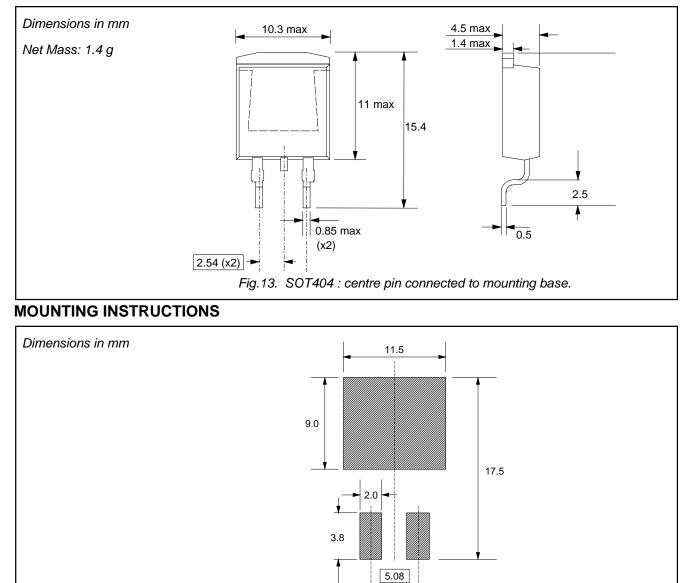


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MECHANICAL DATA



Notes

1. Plastic meets UL94 V0 at 1/8".

Fig.14. SOT404 : minimum pad sizes for surface mounting.

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DEFINITIONS

Data sheet status					
Objective specification	Dbjective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification	cation This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
or more of the limiting val operation of the device at	in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one lues may cause permanent damage to the device. These are stress ratings only and t these or at any other conditions above those given in the Characteristics sections of nplied. Exposure to limiting values for extended periods may affect device reliability.				
Application information	I				
Where application inform	ation is given, it is advisory and does not form part of the specification.				
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